

# INTERNATIONAL DIRECTORY OF PRODUCTION WIRE BONDRERS

<p>Company Name Address ☎ Phone ☎ Fax 📅 Year Founded CM=Consult Manufacturer</p> <p><small>Note: Issue advertisers are listed in boldface type. Information was supplied by the respective companies. For more information, visit <a href="http://www.chipscalereview.com">www.chipscalereview.com</a> or the company's web sites.</small></p>	<p>Model 🕒 Introduced ❖ Bonding Area (X, Y) in mm Package Leadframe Capabilities Ⓛ Length in mm Ⓜ Width in mm Ⓣ Thickness in mm</p>	<p>✖ Bond Pitch Capability <small>in <math>\mu\text{m}@ 3 \text{ sigma}</math></small> Ⓜ Weight in kg Ⓜ Type and Method Ⓟ Bond Placement <small>repeatability in <math>\mu\text{m}@ 3 \text{ sigma}</math></small> Ⓐ Accuracy <small>in <math>\mu\text{m}@ 3 \text{ sigma}</math></small></p>	<p>Ⓢ Footprint <small>(W x D in mm)</small> Ⓜ Material Handling Ⓢ Conversion Time <small>in minutes for same leadframe type</small></p>	<p>Looping Capability Ⓜ Maximum Wire Length in mm Ⓛ Minimum Loop Length in mm ✖ Applications 1. Discretes; 2. Hybrids; 3. ICs; 4. Laser diodes; 5. MCMs/Other modules; 6. MEMS/MOEMS; 7. Opto/Nano 8. Smart cards; 9. Other</p>	<p>[web site] ✖ Contact ☎ Phone ☎ Fax 🌐 Additional Offices</p>
<p><b>ASM Technology Singapore PTE. Ltd.</b> Division of ASM Pacific Technology Singapore ☎ +65.67526311 ☎ +65.67582287 📅 1989</p>	<p>Eagle 60AP 🕒 May 2004 ❖ 54 x 65 @ leadframe width &lt;72mm Ⓛ 140-295 Ⓜ 23-72 without heater block change; 23-90 with block change Ⓣ 0.1-0.8</p>	<p>✖ 30<math>\mu\text{m}</math> BPP Ⓜ 750 Ⓜ Thermosonic/Ball Ⓟ <math>\pm 2.5</math> Ⓐ <math>\pm 2.5</math></p>	<p>Ⓢ 720 x 820 Ⓜ Leadframe, substrate, flat boat, carrier Ⓢ &lt;5 minutes</p>	<p>Ⓜ 8 Ⓛ CM ✖ 1-8</p>	<p>[<a href="http://asmpacific.com">asmpacific.com</a>] ✖ James Song, Product Manager james.song@asmpt.com 🌐 <b>ASM Pacific Assembly Products</b> 97 E. Brokaw Rd. San Jose, CA 95112 ✖ Jerry Dellheim jerry.dellheim@asmpt.com ☎ 408.451.0800</p>
<p><b>F&amp;K Delvotec Bondtechnik GmbH</b> Daimlerstr, 5-7 85521 Ottobrunn, Germany ☎ +49.89.62.9950 ☎ +49.89.62.995100 📅 1978</p>	<p>64000 G5 (Fine Wire Bonder) 🕒 July 2004 ❖ 250 x 200 Ⓛ 100-300 Ⓜ 200 Ⓣ 65</p>	<p>✖ CM Ⓜ 650 Ⓜ Thermosonic/Wedge (Ultrasonic available) Ⓟ 10 Ⓐ 10</p>	<p>Ⓢ 615 x 1090 Ⓜ Auer boat, leadframe, PC board, substrate, tape Ⓢ 10 minutes</p>	<p>Ⓜ 60 (longer, optional) Ⓛ 70<math>\mu\text{m}</math> for 18<math>\mu\text{m}</math> diameter wire ✖ 1-8</p>	<p>[<a href="http://fkdelvotec.com">fkdelvotec.com</a>] ✖ Dr. Farhad Farassat, President farhad.farassat@de.fkdelvotec.com ☎ +49.89.62.995.110 ✖ Desmond Bradley, Sales &amp; Marketing Mgr. Int'l. desmond.bradley@de.fkdelvotec.com 🌐 <b>F&amp;K Delvotec Inc.</b> 27182 Burbank Foothill Ranch, CA 92610 ✖ Rick Bailey, GM rick.bailey@fkdelvotecusa.com 🌐 <b>F&amp;K Delvotec Bondtechnik GmbH &amp; Co. KG</b> Singapore ✖ Philip Tong, BM philip@fkdelvotec.sg</p>
<p>Hesse &amp; Knipps GmbH Vattmannstrasse 6 D-33100 Paderborn, Germany ☎ +49.52.51.1560 📅 1978</p>	<p>Bondjet BJ815 🕒 2002 ❖ 312 x 178 Ⓛ Unlimited Ⓜ 350 Ⓣ 125</p>	<p>✖ &lt;40 Ⓜ 1100 Ⓜ Thermosonic/Ultrasonic Wedge Ⓟ 3 Ⓐ 3</p>	<p>Ⓢ 920 x 1402 Ⓜ Auer boat, J-boat, leadframe, R/R, substrate Ⓢ 2 minutes</p>	<p>Ⓜ 20 Ⓛ 70 ✖ 1-8</p>	<p>[<a href="http://hesse-knipps.com">hesse-knipps.com</a>] 🌐 USA: San Jose Hesse-Knipps Inc. ✖ Joseph Bubel, President bubel@hesse-knipps.com ☎ 408.436.9300</p>
<p><b>Kulicke &amp; Soffa Industries</b> 2101 Blair Mill Rd. Willow Grove, PA 19090 ☎ 215.784.6795 ☎ 215.784.6284 📅 1951</p>	<p>Maxµm Plus Ultra High Speed Ball Bonder 🕒 May 2001 ❖ 56 x 66 Ⓛ 90-267 Ⓜ 15.2-90 Ⓣ 0.1-0.89</p>	<p>✖ 35 Ⓜ 566 Ⓜ CM/Ball Ⓟ CM Ⓐ <math>\pm 2.5</math></p>	<p>Ⓢ 889 x 889 with MHS Ⓜ Auer boat, BGA, leadframe, strip, tape Ⓢ 4 minutes</p>	<p>Ⓜ 7.6 Ⓛ 100 ✖ 1-8</p>	<p>[<a href="http://kns.com">kns.com</a>] ✖ T.C. Mak, Sales Contact tcmak@kns.com ☎ 215.784.6702</p>

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<b>Orthodyne</b> 16700 Red Hill Ave. Irvine, CA 92606 ☎ 949.660.0440 ☎ 949.660.0444 📅 1962	7200 Dual Head Semiconductor Bonder ⌚ June 2002 ❖ 70 x 70 Ⓛ 160-260 Ⓜ 18-72 Ⓣ CM	✖ CM Ⓜ 682 Ⓜ Ultrasonic/Wedge Ⓟ CM Ⓐ $\pm 10$ large wire, $\pm 5$ small wire	Ⓢ 1740 x 1280 Ⓜ Leadframe inline and magazine-to- magazine ⌚ CM	Ⓜ CM Ⓛ CM ✖ 1, 3, 5, power leadframes	<b>[orthodyne.com]</b> ✖ Siegbert Haumann, Product Manager siggi.haumann@orthodyne.com ✖ Matt Vorona, Director of International Sales matt.vorona@orthodyne.com 🌐 Eastern Regional Office 116 Ellsworth Ave. Mineola, NY 11501 ☎ 516.739.2690 ✖ Mike McKeown, Sales Manager mike.mckeown@orthodyne.com
	M360R Large Ribbon Bonder ⌚ December 2003 ❖ 250 x 150 Ⓛ Ⓜ Ⓣ NA (power modules)	✖ CM Ⓜ 320 Ⓜ Ultrasonic/Wedge Ⓟ CM Ⓐ $\pm 15$	Ⓢ 610 x 1095 Ⓜ CM ⌚ CM	Ⓜ CM Ⓛ CM ✖ 9: Automotive, power modules, power leadframes	
	3600Plus Large Wire Bonder ⌚ April 2005 ❖ 250 x 150 (300 x 300 with optional work table) Ⓛ Ⓜ Ⓣ NA (power modules)	✖ CM Ⓜ 400 Ⓜ Ultrasonic/Wedge Ⓟ CM Ⓐ $\pm 10$	Ⓢ 680 x 1308 Ⓜ CM ⌚ CM	Ⓜ CM Ⓛ CM ✖ 1, 2, 5, 6	
	3700Plus Small Wire Wedge Bonder ⌚ April 2005 ❖ 250 x 150 (300 x 300 with optional work table) Ⓛ Ⓜ Ⓣ NA (MCM-type pkgs.)	✖ 75, CM Ⓜ 400 Ⓜ Ultrasonic/Wedge Ⓟ CM Ⓐ $\pm 5$	Ⓢ 680 x 1308 Ⓜ CM ⌚ CM	Ⓜ CM Ⓛ CM ✖ 2, 5	
<b>Palomar Technologies</b> 2728 Loker Ave. West Carlsbad, CA 92008 ☎ 760.931.3600 ☎ 760.931.3444 📅 1975	Model 8080 High Speed Au Ball Bumper ⌚ January 2005 ❖ 300 x 150 Ⓛ CM Ⓜ CM Ⓣ CM	✖ <65 inline @ 3 sigma Ⓜ 820 Ⓜ Thermosonic/Ball Ⓟ $\pm 2.5$ Ⓐ CM	Ⓢ 800 x 800 Ⓜ Auer boat, J-boat, leadframe, substrate, wafer stages ⌚ CM	Ⓜ CM Ⓛ CM ✖ 1-8	<b>[palomartechnologies.com]</b> ✖ Jeffrey King, VP Sales jking@bonders.com 🌐 Palomar Technologies GmbH Erlangen, Germany ✖ Josef Schmid, Managing Director, Europe jschmid@bonders.com 🌐 Palomar Technologies Pte Singapore ✖ Wai Seng Chew, Director, Asia wschew@bonders.com
	Model 8030 High Speed Au Ball Bumper ⌚ January 2005 ❖ 300 x 150 Ⓛ CM Ⓜ CM Ⓣ CM	✖ <65 inline @ 3 sigma Ⓜ 820 Ⓜ Thermosonic/ Ball-Stitch Ⓟ $\pm 2.5$ Ⓐ CM	Ⓢ 800 x 800 Ⓜ Auer boat, J-boat, leadframe, substrate, wafer stages ⌚ CM	Ⓜ CM Ⓛ CM ✖ 1-8	
Shinkawa Ltd. Tokyo, Japan ☎ +81.42.560.1241 📅 1959	UTC-1000 Super ⌚ July 2004 ❖ 56 x 66 Ⓛ 95-262 Ⓜ 20-80 Ⓣ 0.07-2.0	✖ 40 Ⓜ 590 Ⓜ Thermosonic/Ball Ⓟ CM Ⓐ $\pm 2.5$	Ⓢ 700 x 700 Ⓜ Auer boat, leadframe, substrate ⌚ 3 minutes	Ⓜ 8 Ⓛ 300 ✖ 3, 5	[shinkawa.com] ✖ USA: Doug Day, GM d_day@shinkawausa.com ☎ 480.831.7988
<b>Unaxis USA Inc.</b> Assembly & Packaging Division, ESEC 1407 W. Drivers Way Tempe, AZ 85284 ☎ 602.893.6990 ☎ 602.893.6793 📅 1976	3100 ⌚ July 2003 ❖ 52 x 70 Ⓛ 100-2700 Ⓜ 15-84 Ⓣ 0.1-0.8	✖ CM Ⓜ 590 Ⓜ Thermosonic/Ball Ⓟ CM Ⓐ $\pm 2.5$	Ⓢ 850 x 960 Ⓜ Flat boat, leadframe ⌚ CM	Ⓜ 9 Ⓛ 75 ✖ 1, 3, 5, 8	<b>[unaxis.com], [esec.com]</b> ✖ Greg Harding greg.harding@unaxis.com ☎ 480.753.1011 ✖ Bob Most, Bob Most Associates Mendam, NJ bob@bobmostassoc.com